

ABSTRACT

Hollow Fiber Membrane Module, its Potting Material and
Chemical Deaeration Method

The present invention relates to a hollow fiber membrane module and its potting material used for chemical deaeration in a semiconductor production process, printers, liquid crystal sealing process or chemical production process and so forth, and to a chemical deaeration method using said hollow fiber membrane module. The hollow fiber membrane module 1 of the present invention is characterized by potting material 2 being an epoxy resin cured product in which the weight change per unit surface area of a potting material test piece after immersing said test piece in a chemical for 6 months at room temperature is within the range of -20 to $+20$ mg/cm², and housing 4 being a polyolefin in which the weight change per unit surface area of a test piece after immersing said test piece in a chemical for 6 months at room temperature is within the range of -20 to $+20$ mg/cm², and the total metal content is 300 ppm or less, said module being able to be used for chemical treatment for a long period of time without the occurrence of leakage from the module.